

# SOT1328-1

plastic thin fine-pitch ball grid array package; 80 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA80
<b>Package type industry code</b>	TFBGA80
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-7-2012

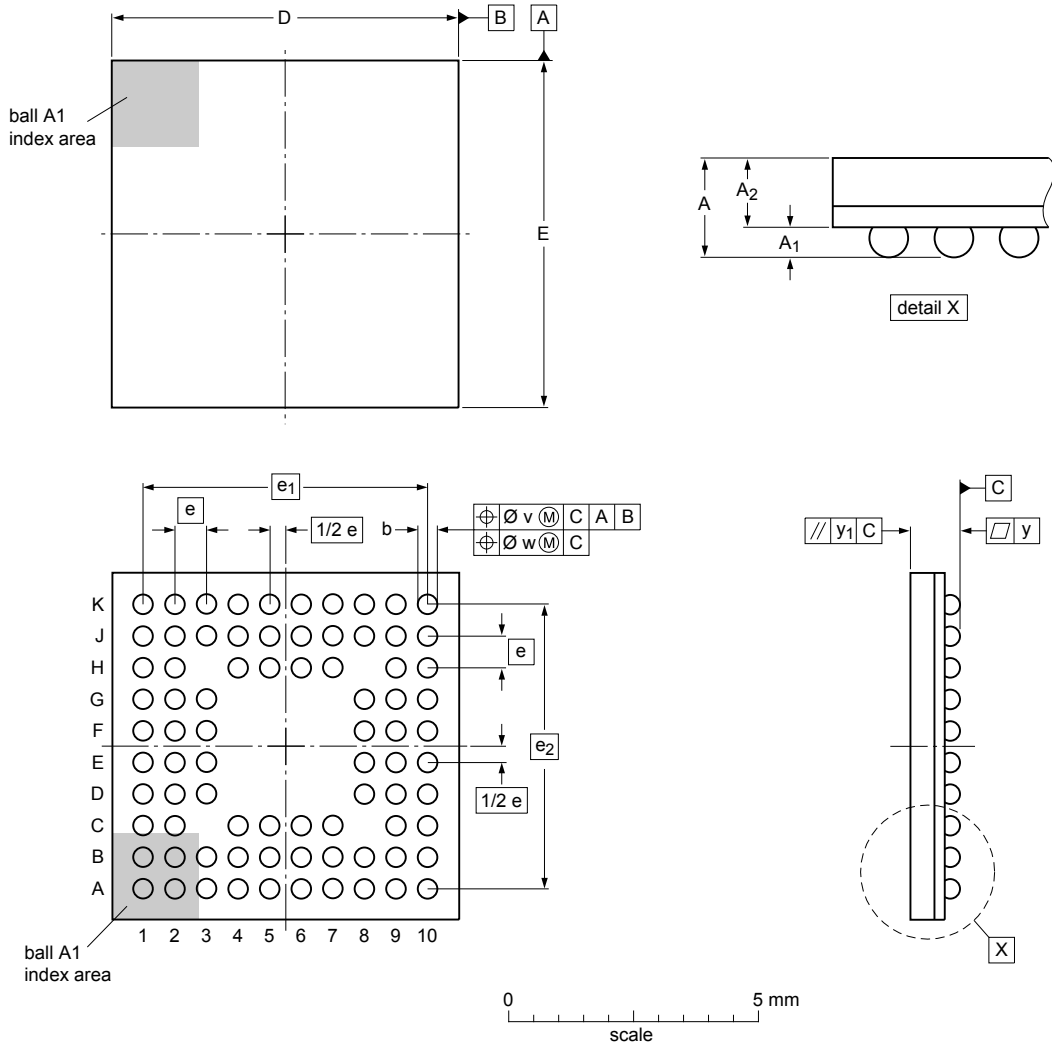
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.9	-	1	1.15	mm
A <sub>2</sub>	package height	0.65	-	0.7	0.8	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	80	-	



2. Package outline

TFBGA80: plastic thin fine-pitch ball grid array package; 80 balls SOT1328-1



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
max	1.15	0.35	0.80	0.45	7.1	7.1							
mm nom	1.00	0.30	0.70	0.40	7.0	7.0	0.65	5.85	5.85	0.15	0.05	0.08	0.1
min	0.90	0.25	0.65	0.35	6.9	6.9							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1328-1					12-05-07- 12-06-14

Fig. 1. Package outline TFBGA80 (SOT1328-1)

### 3. Legal information

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